

Ball / Land Grid Array Sockets

Knob Lock Type

(patents pending)



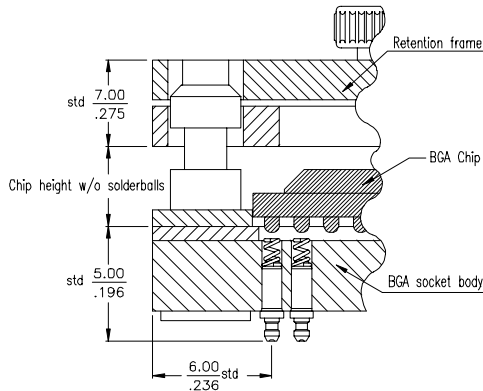
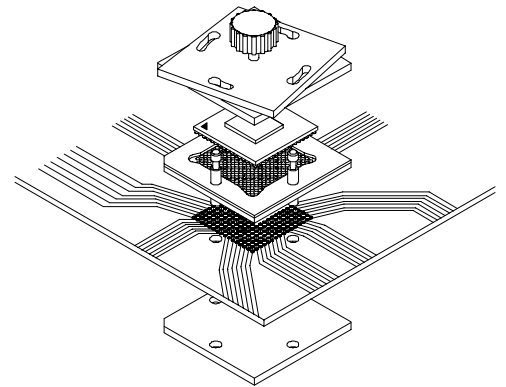
E-tec is now the leading BGA socket manufacturer.

Sockets range from 19 x 19 upwards contacts with even larger parts currently in design. Some of the existing patterns are shown on the following pages, many more exist and your exact requirements can easily be added to our extensive product library. The SMD socket is simply placed and reflowed onto the PCB in the same way as the chip and occupies only a small amount of additional board space. The knob lock socket extends ≈ 6,00 mm beyond the outer ballrow with no fixing holes.

We aim to solve your requirements - many different terminals and configurations are available. Your custom sets our standards!

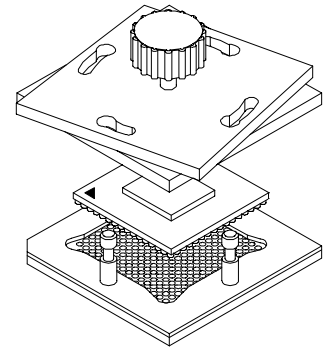
Please note, we will always request the chip data to ensure we offer a compatible socket.

solderless compression type



dimensions if contact type 30

SMT and soldertail type



<p>SMT Style</p> <p>PCB Layout</p> <p>Pitch</p> <p>∅ 0.70 / .028</p>	<p>Soldertail Style</p> <p>PCB Layout</p> <p>Pitch</p> <p>∅ 0.60 / .024</p>	<p>Specifications</p> <p>Mechanical data</p> <p>Contact life: min. 100000 cycles</p> <p>Retention System life: 1000 cycles min.</p> <p>Solderability: exceeds MIL-STD-202 Method 208</p> <p>Individual contact force: 40 grams max.</p> <p>Material</p> <p>Insulator: Glass Epoxy FR 4</p> <p>Terminal: Brass</p> <p>Contact: BeCu</p> <p>Electrical data</p> <p>Contact resistance: < 30 mΩ</p> <p>Current rating: 1 A max.</p> <p>Insulation resistance at 500V DC: > 10⁴ MΩ</p> <p>Breakdown voltage at 60 Hz: 1 KV min.</p> <p>Operating temperature</p> <p>-55°C to +150°C ; 220°C for 10 sec.</p>
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The pitch dimension depends on your Ball Grid Array

How to order

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<p>Device Type</p> <p>B = Ball Grid</p> <p>L = Land Grid</p> <p>C = Column Grid</p>	<p>Device Material</p> <p>C = Ceramic</p> <p>P = Plastic</p>	<p>Pitch</p> <p>10 = 1,00mm</p> <p>12 = 1,27mm</p> <p>15 = 1,50mm</p>	<p>Grid Code</p> <p><i>please refer to the footprint pages</i></p>	<p>Config Code</p> <p><i>will be given by the factory after receipt of the chip datasheet</i></p>	<p>Plating</p> <p>01 = tin/gold</p> <p>11 = gold</p> <p><i>only for solderless Compression Type</i></p>
<p>Nbr of contacts</p> <p><i>refer to the next pages</i></p>		<p>Contact Type</p> <p>30 = standard SMD („A“ = 1,20/.047)</p> <p>29 = raised SMD („A“ = 5,00/.197)</p> <p>70 = solder tail</p> <p>90 = solderless Compression Type</p>			